

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	199641	((heat\$3 therm\$5 temperature) near2 (electric\$4 spread\$4 or dissipat\$4 releas\$3 sink)) or thermoelectric\$3 or electric\$3therm\$4) and (die or chip or "IC" or device) and (cold or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:57
L10	16249	9 and (((heat\$3 therm\$5 temperature) near2 electric\$4) or thermo\$3electric\$3 or electric\$3therm\$4) with (convert\$4 or exchange\$4)) or peltier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:45
L11	10285	10 and (substrate wafer board "PCB" "PWB" base)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:46
L12	8432	11 and (convert\$3 or exchange\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:49
L13	6691	11 and ((heat therm\$4) with (convert\$3 or exchange\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:49
L14	5330	13 and (@ad<"20031021" or @rlad<"20031021")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:51
L15	3960	14 and ((chip die "IC" device) with (heat\$3 therm\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:54
L16	2554	15 and ((substrate wafer board "PWB" "PCB" base) with (heat\$3 therm\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:55
L17	1462	16 and (cold or cool\$4) and hot	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:59
L19	953	17 and ((cold or cool\$4) with (die chip "IC" device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:00
L20	398	16 and ((hot) with (substrate wafer base board "PWB" "PCB"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:27

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L21	229	19 and ((hot) with (substrate wafer base board "PWB" "PCB"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:01
L22	724	19 not 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:37
S1	1488	257/714.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:51
S2	293	257/716.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 16:37
S3	2681	257/712.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:55
S4	2892	257/707,721,796,e23.08,e23.087,e23.097,e31.131.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:09
S5	2586	S4 and (heat therm\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:33
S6	35	(US-20050059238-\$ or US-20060001153-\$ or US-20050085075-\$ or US-20030184941-\$ or US-20030179549-\$ or US-20060071227-\$).did. or (US-6262357-\$ or US-6588217-\$ or US-7034394-\$ or US-6893902-\$ or US-6614109-\$ or US-6586835-\$ or US-6455930-\$ or US-5955781-\$ or US-5637921-\$ or US-5229643-\$ or US-6613602-\$ or US-6222113-\$ or US-5956569-\$ or US-5724818-\$ or US-5712448-\$ or US-5040381-\$ or US-6818817-\$ or US-5966941-\$ or US-6740600-\$ or US-6387742-\$ or US-5419780-\$ or US-6100199-\$ or US-6525419-\$ or US-5921087-\$ or US-7061104-\$ or US-6432809-\$).did. or (US-6639242-\$ or US-6711904-\$ or US-7084495-\$).did.	US-PGPUB; USPAT	OR	ON	2006/08/01 13:32
S14	2892	257/707,721,796,e23.08,e23.087,e23.097,e31.131.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:05
S15	14	S14 and ((thermoelectric\$3 or (therm\$4 near3 electric\$4)) same convert\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:11

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S16	32	S14 and ((thermoelectric\$3 or (therm\$4 near3 electric\$4)) same (convert\$4 exchang\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:22
S17	540	(S14 not (S15 S16)) and ((thermoelectric\$3 or (therm\$4 near3 electric\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:22
S18	411	S17 and (heat thermo\$4) and (chip die "IC" (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:25
S19	339	S18 and ((heat thermo\$4 temperatur\$4) with (releas\$4 spread\$4 exchang\$4 convert\$4 sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:32
S20	205	S19 and (cold or cool\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:33
S21	13	"6408937"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 19:46